

Features

- Low Gate Charge
- Low $R_{DS(ON)}$:
 - 30 m Ω @ $V_{GS} = 10V$
 - 40 m Ω @ $V_{GS} = 4.5V$
- Low Input/Output Leakage
- **Lead Free By Design/RoHS Compliant (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **"Green" Device (Note 4)**

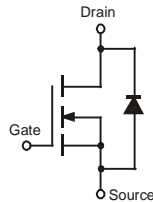
Mechanical Data

- Case: SC-59
- Case Material - Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.008 grams (approximate)

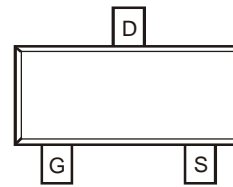
SC-59



Top View



Equivalent Circuit



Pin Configuration

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current (Note 1) Continuous	I_D	6	A
$T_A = 25^\circ\text{C}$		5	
$T_A = 70^\circ\text{C}$			
Pulsed Drain Current (Note 2)	I_{DM}	24	A
Body-Diode Continuous Current (Note 1)	I_S	2.25	A

Thermal Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 1)	P_D	1.4	W
Thermal Resistance, Junction to Ambient (Note 1) $t \leq 10s$	$R_{\theta JA}$	90	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ\text{C}$

- Notes:
1. Device mounted on 1"x1", FR-4 PC board with 2 oz. Copper and test pulse width $t \leq 10s$.
 2. Repetitive Rating, pulse width limited by junction temperature.
 3. No purposefully added lead.
 4. Diodes Inc's "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
STATIC PARAMETERS						
Drain-Source Breakdown Voltage	BV _{DSS}	30	—	—	V	I _D = 250μA, V _{GS} = 0V
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 30V, V _{GS} = 0V
Gate-Body Leakage Current	I _{GSS}	—	—	±100	nA	V _{DS} = 0V, V _{GS} = ±20V
Gate Threshold Voltage	V _{GS(th)}	1.0	—	2.1	V	V _{DS} = V _{GS} , I _D = 250μA
Static Drain-Source On-Resistance (Note 5)	R _{DS(on)}	—	25 36	30 40	mΩ	V _{GS} = 10V, I _D = 6A V _{GS} = 4.5V, I _D = 5A
Forward Transconductance (Note 5)	g _{FS}	—	5	—	S	V _{DS} = 10V, I _D = 8A
Diode Forward Voltage (Note 5)	V _{SD}	—	0.7	1.1	V	I _S = 2.25A, V _{GS} = 0V
DYNAMIC PARAMETERS (Note 6)						
Total Gate Charge	Q _g	—	10.5	—	nC	V _{GS} = 5V, V _{DS} = 15V, I _D = 6A
Gate-Source Charge	Q _{gs}	—	3.8	—	nC	V _{GS} = 10V, V _{DS} = 15V, I _D = 6A
Gate-Drain Charge	Q _{gd}	—	2.9	—	nC	V _{GS} = 10V, V _{DS} = 15V, I _D = 6A
Turn-On Delay Time	t _{D(on)}	—	11	—	ns	V _{DD} = 15V, V _{GS} = 10V, R _D = 1.8Ω, R _G = 6Ω
Turn-On Rise Time	t _r	—	7	—	ns	
Turn-Off Delay Time	t _{D(off)}	—	63	—	ns	
Turn-Off Fall Time	t _f	—	30	—	ns	
Input Capacitance	C _{iss}	—	755	—	pF	V _{DS} = 10V, V _{GS} = 0V f = 1.0MHz
Output Capacitance	C _{oss}	—	136	—	pF	
Reverse Transfer Capacitance	C _{rss}	—	108	—	pF	

Notes: 5. Test pulse width t = 300ms.
6. Guaranteed by design. Not subject to production testing.

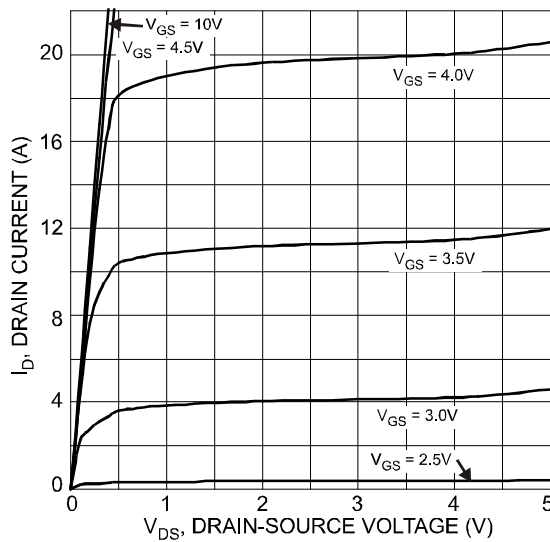


Fig. 1 Typical Output Characteristics

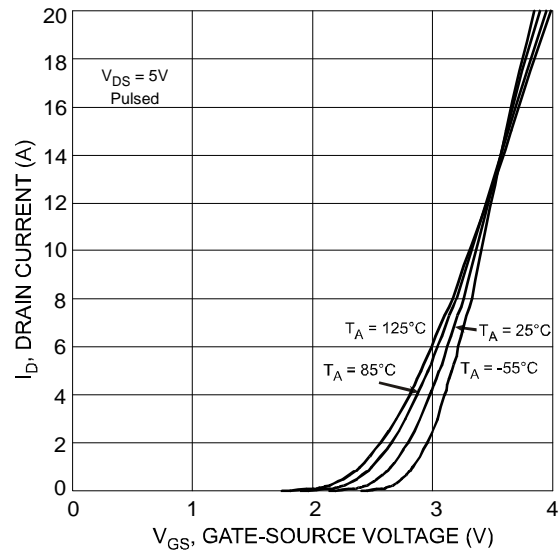


Fig. 2 Typical Transfer Characteristics

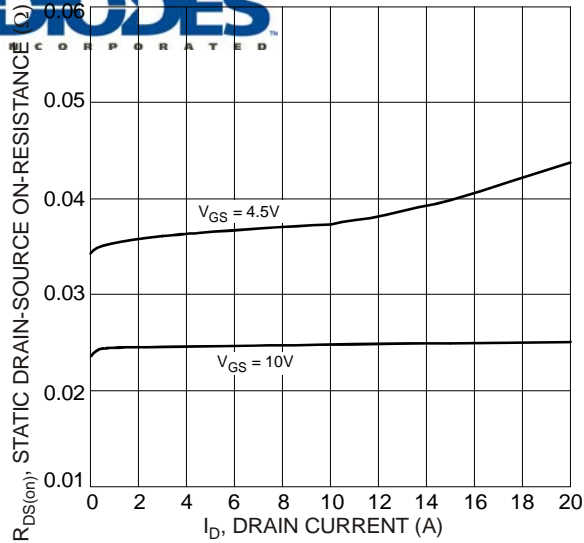


Fig. 3 On-Resistance vs. Drain Current and Gate Voltage

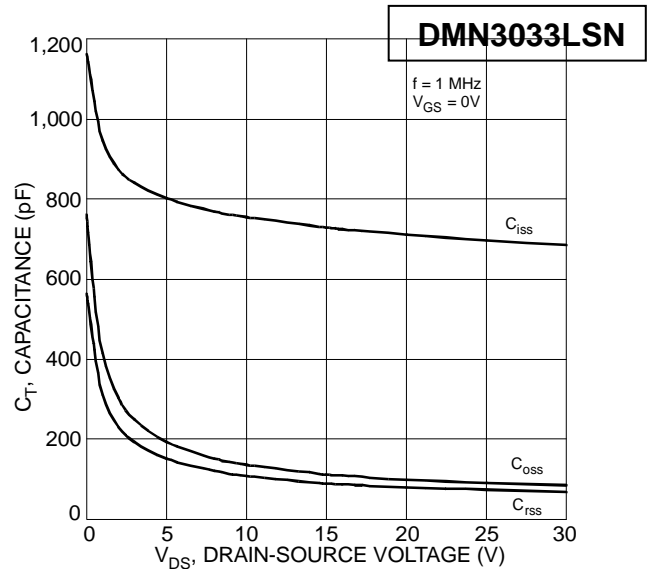


Fig. 4 Typical Total Capacitance

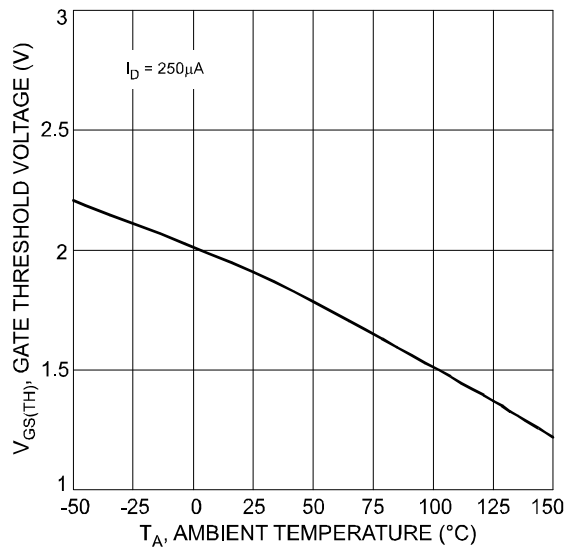


Fig. 5 Gate Threshold Voltage vs. Ambient Temperature

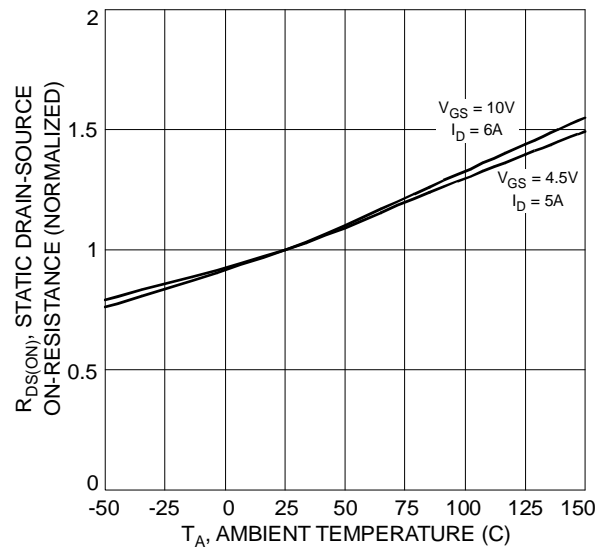


Fig. 6 Normalized Static Drain-Source On-Resistance vs. Ambient Temperature

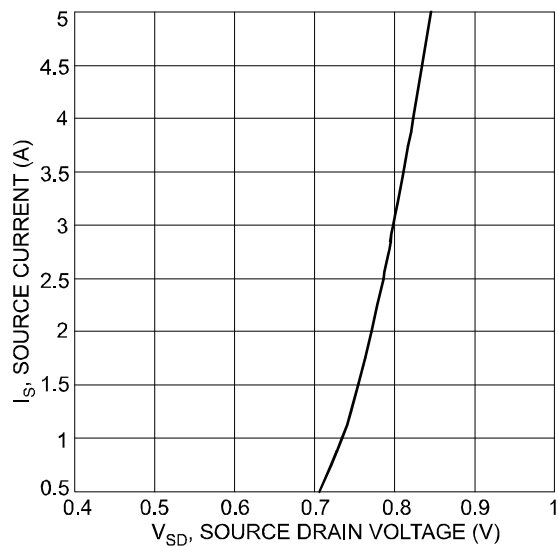
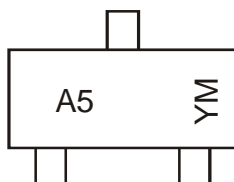


Fig. 7 Reverse Drain Current vs. Source-Drain Voltage

Part Number	Case	Packaging
DMN3033LSN-7	SC-59	3000/Tape & Reel

Notes: 7. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



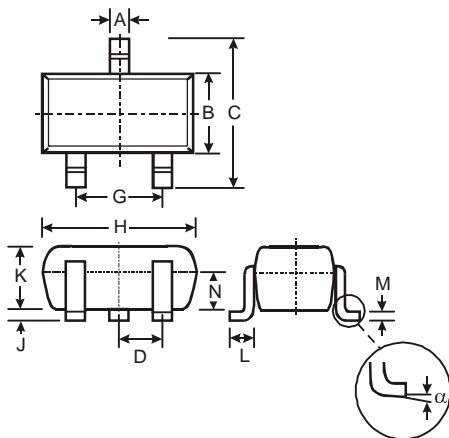
A5 = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: U = 2007)
M = Month (ex: 9 = September)

Date Code Key

Year	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	U	V	W	X	Y	Z	A	B	C

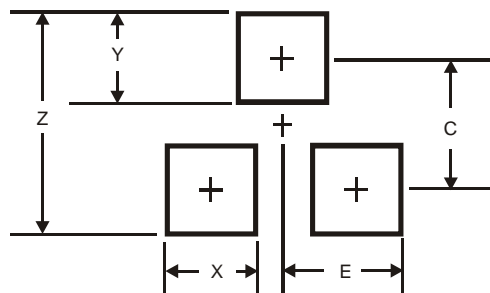
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Package Outline Dimensions



SC-59			
Dim	Min	Max	Typ
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	-	-	0.95
G	-	-	1.90
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
N	0.70	0.80	0.75
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	3.4
X	0.8
Y	1.0
C	2.4
E	1.35

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2. support or sustain life and whose failure to perform when properly used in accordance with instructions for use provided in the labeling can be reasonably expected to result in significant injury to the user.

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